

# Product Specification

XBLW SN74LS10

Triple 3-input Nand Gate

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## Description

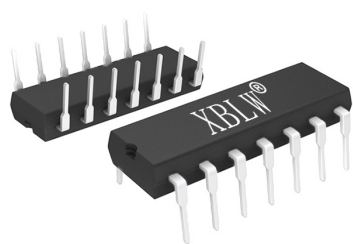
The SN74LS10 is a triple 3-input NAND gate. Inputs include clamp diodes. This enables the use of current limiting resistors to interface inputs to voltages in excess of  $V_{CC}$ .

## Features

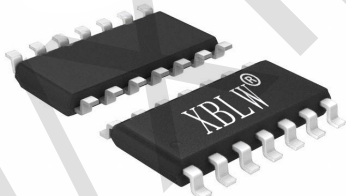
- Buffered inputs
- Wide operating voltage range: 2 V to 6 V
- Specified from -20°C to +85°C
- Packaging information: DIP-14/SOP-14/TSSOP-14

## Applications

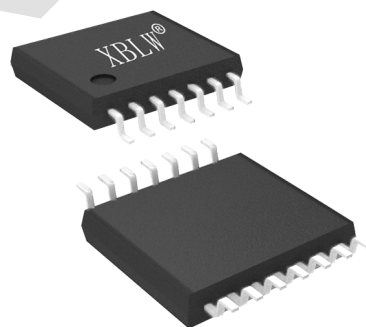
- Alarm / tamper detect circuit
- S-R latch



DIP-14



SOP-14



TSSOP-14

## Ordering Information

Product Model	Package Type	Marking	Packing	Packing Qty
XBLW SN74LS10N	DIP-14	74LS10N	Tube	1000Pcs/Box
XBLW SN74LS10DTR	SOP-14	74LS10	Tape	2500Pcs/Reel
XBLW SN74LS10TDTR	TSSOP-14	74LS10	Tape	3000Pcs/Reel

### Block Diagram

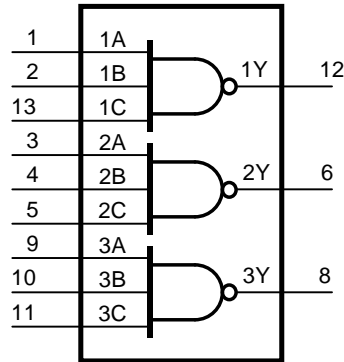


Figure 1. Logic symbol

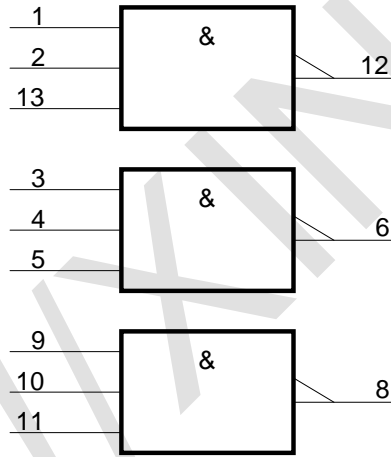


Figure 2. IEC logic symbol

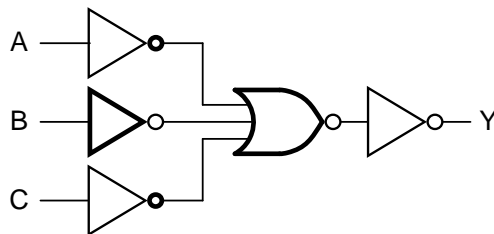
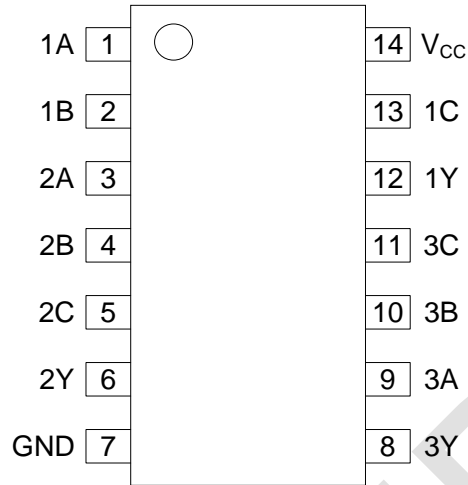


Figure 3. Logic diagram for one gate

## Pin Configurations



## Pin Description

Pin No.	Pin Name	Description
1	1A	data input
2	1B	data input
3	2A	data input
4	2B	data input
5	2C	data input
6	2Y	data output
7	GND	ground (0V)
8	3Y	data output
9	3A	data input
10	3B	data input
11	3C	data input
12	1Y	data output
13	1C	data input
14	V <sub>cc</sub>	supply voltage

## Function Table

Input			Output
nA	nB	nC	nY
L	X	X	H
X	L	X	H
X	X	L	H
H	H	H	L

Note: H=HIGH voltage level; L=LOW voltage level; X=don't care.

## Electrical Parameter

### Absolute Maximum Ratings

(Voltages are referenced to GND(ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Max.	Unit
supply voltage	$V_{CC}$	-	-0.5	+7	V
input clamping current	$I_{IK}$	$V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$	-	$\pm 20$	mA
output clamping current	$I_{OK}$	$V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$	-	$\pm 20$	mA
output current	$I_O$	$-0.5V < V_O < V_{CC} + 0.5V$	-	$\pm 25$	mA
supply current	$I_{CC}$	-	-	50	mA
ground current	$I_{GND}$	-	-50	-	mA
total power dissipation	$P_{tot}$	-	-	500	mW
storage temperature	$T_{stg}$	-	-65	+150	°C
soldering temperature	$T_L$	10s	DIP	245	°C
			SOP/TSSOP	260	

### Recommended Operating Conditions

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
supply voltage	$V_{CC}$	-	2.0	5.0	6.0	V
input voltage	$V_I$	-	0	-	$V_{CC}$	V
output voltage	$V_O$	-	0	-	$V_{CC}$	V
input transition rise and fall rate	$\Delta t / \Delta V$	$V_{CC} = 2.0V$	-	-	625	ns/V
		$V_{CC} = 4.5V$	-	1.67	139	ns/V
		$V_{CC} = 6.0V$	-	-	83	ns/V
ambient temperature	$T_{amb}$	-	-20	-	+85	°C

### Electrical Characteristics

#### DC Characteristics 1

( $T_{amb}=25^{\circ}\text{C}$ , voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit	
HIGH-level input voltage	$V_{IH}$	$V_{CC}=2.0\text{V}$	1.5	1.2	-	V	
		$V_{CC}=4.5\text{V}$	3.15	2.4	-	V	
		$V_{CC}=6.0\text{V}$	4.2	3.2	-	V	
LOW-level input voltage	$V_{IL}$	$V_{CC}=2.0\text{V}$	-	0.8	0.5	V	
		$V_{CC}=4.5\text{V}$	-	2.1	1.35	V	
		$V_{CC}=6.0\text{V}$	-	2.8	1.8	V	
HIGH-level output voltage	$V_{OH}$	$V_I=V_{IH}$ or $V_{IL}$	$I_O=-20\mu\text{A}; V_{CC}=2.0\text{V}$	1.9	2.0	-	V
			$I_O=-20\mu\text{A}; V_{CC}=4.5\text{V}$	4.4	4.5	-	V
			$I_O=-20\mu\text{A}; V_{CC}=6.0\text{V}$	5.9	6.0	-	V
			$I_O=-4.0\text{mA}; V_{CC}=4.5\text{V}$	3.98	4.32	-	V
			$I_O=-5.2\text{mA}; V_{CC}=6.0\text{V}$	5.48	5.81	-	V
LOW-level output voltage	$V_{OL}$	$V_I=V_{IH}$ or $V_{IL}$	$I_O=20\mu\text{A}; V_{CC}=2.0\text{V}$	-	0	0.1	V
			$I_O=20\mu\text{A}; V_{CC}=4.5\text{V}$	-	0	0.1	V
			$I_O=20\mu\text{A}; V_{CC}=6.0\text{V}$	-	0	0.1	V
			$I_O=4.0\text{mA}; V_{CC}=4.5\text{V}$	-	0.15	0.26	V
			$I_O=5.2\text{mA}; V_{CC}=6.0\text{V}$	-	0.16	0.26	V
input leakage current	$I_I$	$V_I=V_{CC}$ or GND; $V_{CC}=6.0\text{V}$	-	-	$\pm 1$	$\mu\text{A}$	
supply current	$I_{CC}$	$V_I=V_{CC}$ or GND; $I_O=0\text{A}; V_{CC}=6.0\text{V}$	-	-	2.0	$\mu\text{A}$	
input capacitance	$C_I$	-	-	3.5	-	pF	

#### DC Characteristics 2

( $T_{amb}=-20^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$ , voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit	
HIGH-level input voltage	$V_{IH}$	$V_{CC}=2.0\text{V}$	1.5	-	-	V	
		$V_{CC}=4.5\text{V}$	3.15	-	-	V	
		$V_{CC}=6.0\text{V}$	4.2	-	-	V	
LOW-level input voltage	$V_{IL}$	$V_{CC}=2.0\text{V}$	-	-	0.5	V	
		$V_{CC}=4.5\text{V}$	-	-	1.35	V	
		$V_{CC}=6.0\text{V}$	-	-	1.8	V	
HIGH-level output voltage	$V_{OH}$	$V_I=V_{IH}$ or $V_{IL}$	$I_O=-20\mu\text{A}; V_{CC}=2.0\text{V}$	1.9	-	-	V
			$I_O=-20\mu\text{A}; V_{CC}=4.5\text{V}$	4.4	-	-	V
			$I_O=-20\mu\text{A}; V_{CC}=6.0\text{V}$	5.9	-	-	V
			$I_O=-4.0\text{mA}; V_{CC}=4.5\text{V}$	3.84	-	-	V
			$I_O=-5.2\text{mA}; V_{CC}=6.0\text{V}$	5.34	-	-	V
LOW-level output voltage	$V_{OL}$	$V_I=V_{IH}$ or $V_{IL}$	$I_O=20\mu\text{A}; V_{CC}=2.0\text{V}$	-	-	0.1	V
			$I_O=20\mu\text{A}; V_{CC}=4.5\text{V}$	-	-	0.1	V
			$I_O=20\mu\text{A}; V_{CC}=6.0\text{V}$	-	-	0.1	V
			$I_O=4.0\text{mA}; V_{CC}=4.5\text{V}$	-	-	0.33	V
			$I_O=5.2\text{mA}; V_{CC}=6.0\text{V}$	-	-	0.33	V
input leakage current	$I_I$	$V_I=V_{CC}$ or GND; $V_{CC}=6.0\text{V}$	-	-	$\pm 1$	$\mu\text{A}$	
supply current	$I_{CC}$	$V_I=V_{CC}$ or GND; $I_O=0\text{A}; V_{CC}=6.0\text{V}$	-	-	20	$\mu\text{A}$	

### AC Characteristics 1

( $T_{amb}=25^{\circ}C$ , voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit	
nA, nB, nC to nY propagation delay	$t_{pd}$	see Figure 5 <sup>[1]</sup>	$V_{CC}=2.0V$	-	30	95	ns
			$V_{CC}=4.5V$	-	11	19	ns
			$V_{CC}=5.0V; C_L=15pF$	-	9	-	ns
			$V_{CC}=6.0V$	-	9	16	ns
transition time	$t_t$	see Figure 5 <sup>[2]</sup>	$V_{CC}=2.0V$	-	19	75	ns
			$V_{CC}=4.5V$	-	7	15	ns
			$V_{CC}=6.0V$	-	6	13	ns
power dissipation capacitance	$C_{PD}$	per package; $V_I= GND$ to $V_{CC}$ <sup>[3]</sup>	-	12	-	pF	

Note:

[1]  $t_{pd}$  is the same as  $t_{PLH}$  and  $t_{PHL}$ .

[2]  $t_t$  is the same as  $t_{THL}$  and  $t_{TLH}$ .

[3]  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in uW).

$$P_D=(C_{PD} \times V_{CC}^2 \times f_i \times N) + \Sigma(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

$f_i$ =input frequency in MHz;

$f_o$ =output frequency in MHz;

$C_L$ =output load capacitance in pF;

$V_{CC}$ =supply voltage in V;

$N$ =number of inputs switching;

$\Sigma(C_L \times V_{CC}^2 \times f_o)$ =sum of outputs.

### AC Characteristics 2

( $T_{amb}=-20^{\circ}C$  to  $+85^{\circ}C$ , voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit	
nA, nB, nC to nY propagation delay	$t_{pd}$	see Figure 5 <sup>[1]</sup>	$V_{CC}=2.0V$	-	-	120	ns
			$V_{CC}=4.5V$	-	-	24	ns
			$V_{CC}=6.0V$	-	-	20	ns
transition time	$t_t$	see Figure 5 <sup>[2]</sup>	$V_{CC}=2.0V$	-	-	95	ns
			$V_{CC}=4.5V$	-	-	19	ns
			$V_{CC}=6.0V$	-	-	16	ns

Note:

[1]  $t_{pd}$  is the same as  $t_{PLH}$  and  $t_{PHL}$ .

[2]  $t_t$  is the same as  $t_{THL}$  and  $t_{TLH}$ .

## Testing Circuit

### AC Testing Circuit

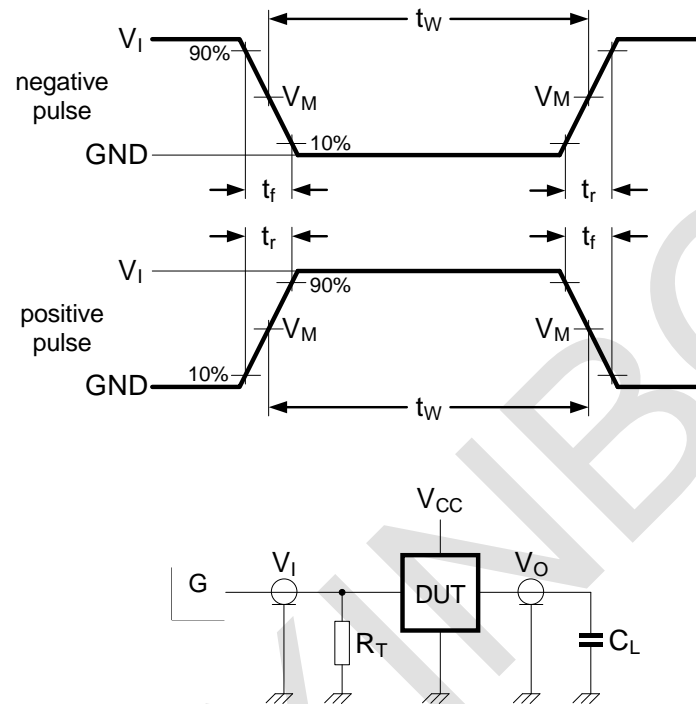


Figure 4. Test circuit for measuring switching times

Definitions for test circuit:

$C_L$ =load capacitance including jig and probe capacitance.

$R_T$ =termination resistance should be equal to the output impedance  $Z_o$  of the pulse generator.



**AC Testing Waveforms**

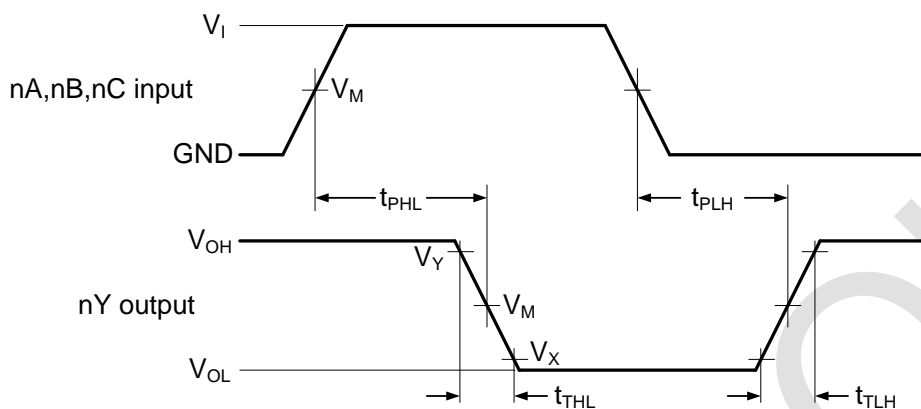


Figure 5. Input to output propagation delays

**Measurement Points**

Type	Input		Output	
	$V_M$	$V_M$	$V_X$	$V_Y$
SN74LS10	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	$0.1 \times V_{CC}$	$0.9 \times V_{CC}$

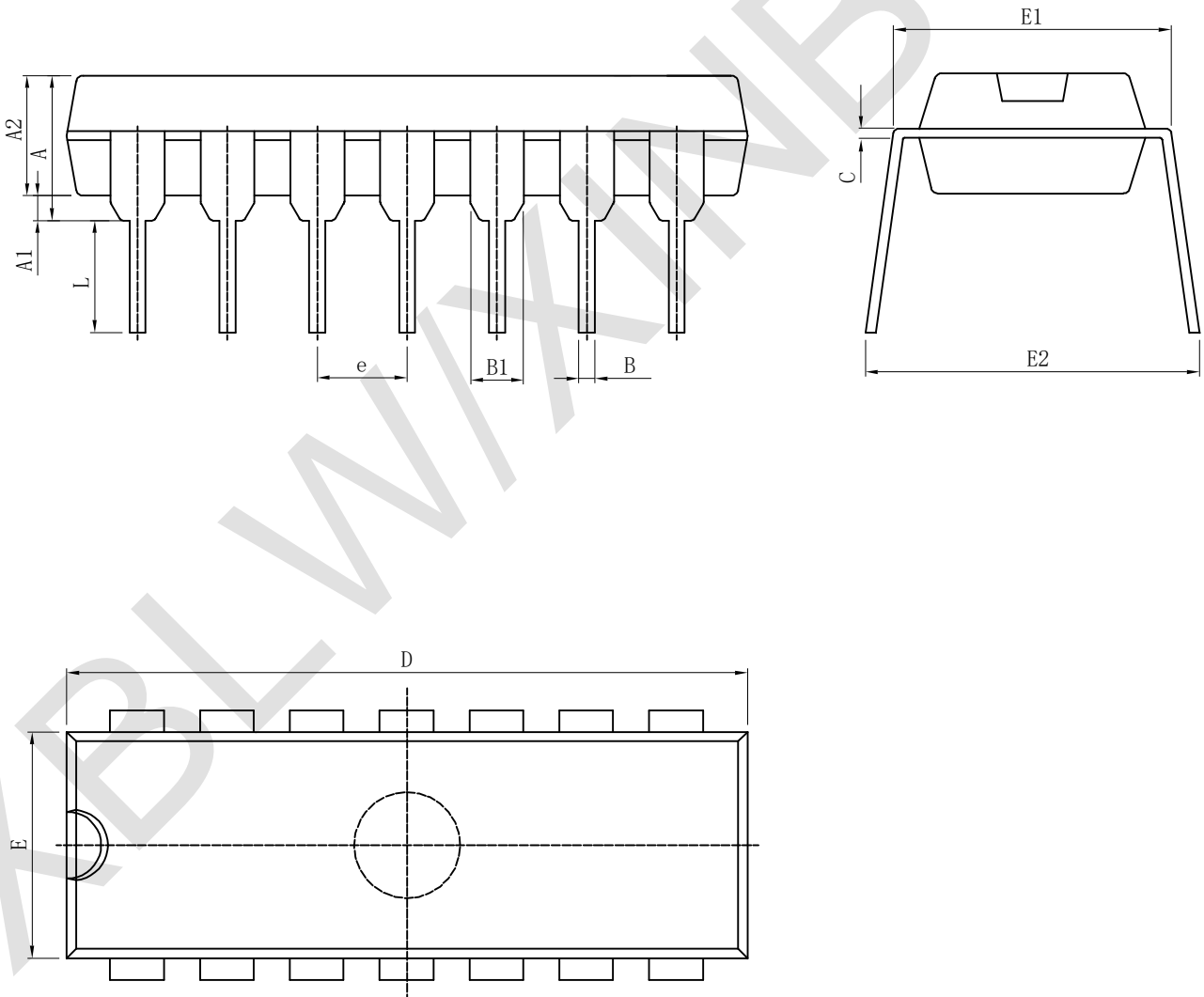
**Test Data**

Type	Input		Load	Test
	$V_I$	$t_r, t_f$	$C_L$	
SN74LS10	$V_{CC}$	6.0ns	15pF, 50pF	$t_{PLH}, t_{PHL}$

**Package Information**

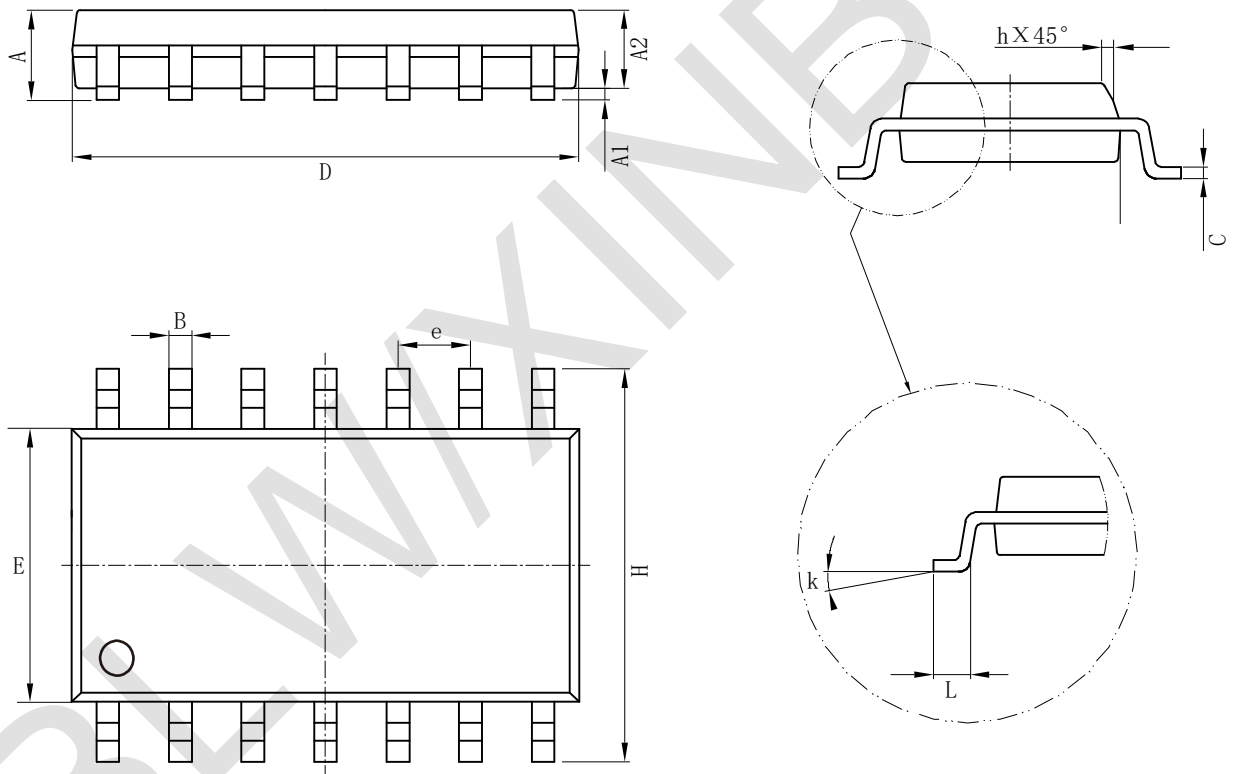
· DIP-14

Size Symbol	Dimensions In Millimeters		Size Symbol	Dimensions In Inches	
	Min (mm)	Max (mm)		Min (in)	Max (in)
A	3.710	4.310	A	0.146	0.170
A1	0.510		A1	0.020	
A2	3.200	3.600	A2	0.126	0.142
B	0.380	0.570	B	0.015	0.022
B1	1.524 (BSC)		B1	0.060 (BSC)	
C	0.204	0.360	C	0.008	0.014
D	18.800	19.200	D	0.740	0.756
E	6.200	6.600	E	0.244	0.260
E1	7.320	7.920	E1	0.288	0.312
e	2.540 (BSC)		e	0.100 (BSC)	
L	3.000	3.600	L	0.118	0.142
E2	8.400	9.000	E2	0.331	0.354



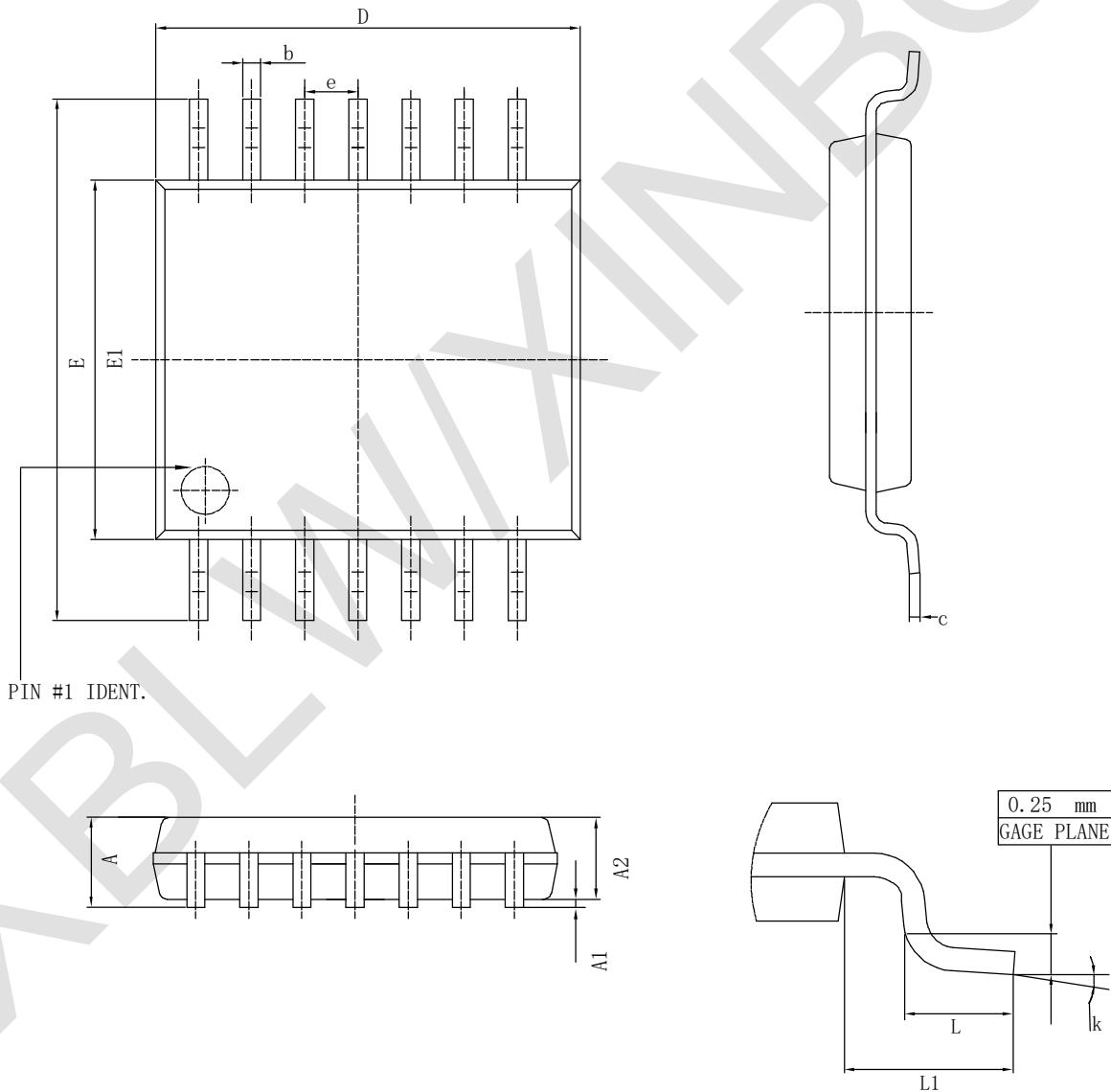
· SOP-14

Symbol	Dimensions In Millimeters		Symbol	Dimensions In Inches	
	Min (mm)	Max (mm)		Min (in)	Max (in)
A	1.350	1.750	A	0.050	0.068
A1	0.100	0.250	A1	0.004	0.009
A2	1.100	1.650	A2	0.040	0.060
B	0.330	0.510	B	0.010	0.020
C	0.190	0.250	C	0.007	0.009
D	8.550	8.750	D	0.330	0.340
E	3.800	4.000	E	0.150	0.150
e	1.27		e	0.05	
H	5.800	6.200	H	0.220	0.240
h	0.250	0.500	h	0.009	0.020
L	0.400	1.270	L	0.015	0.050
k	8° (max)		k	8° (max)	



· TSSOP-14

Size Symbol	Dimensions In Millimeters		Size Symbol	Dimensions In Inches	
	Min(mm)	Max(mm)		Min(in)	Max(in)
A		1.200	A		0.047
A1	0.050	0.150	A1	0.002	0.006
A2	0.800	1.050	A2	0.031	0.041
b	0.190	0.300	b	0.007	0.012
c	0.090	0.200	c	0.004	0.0089
D	4.900	5.100	D	0.193	0.201
E	6.200	6.600	E	0.244	0.260
E1	4.300	4.500	E1	0.169	0.176
e	0.65		e	0.0256	
L	0.450	0.750	L	0.018	0.030
L1	1.00		L1	0.039	
k	0°	8°	k	0°	8°



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